

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
4 March 2004 (04.03.2004)

PCT

(10) International Publication Number  
**WO 2004/019195 A2**

(51) International Patent Classification<sup>7</sup>: **G06F 1/26**

(21) International Application Number:  
PCT/US2003/026429

(22) International Filing Date: 21 August 2003 (21.08.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
10/227,125 23 August 2002 (23.08.2002) US

(71) Applicant: **INTEL CORPORATION** [US/US]; 2200  
Mission College Boulevard, Santa Clara, CA 95052 (US).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(72) Inventors: **RUSU, Stefan**; 1050 Eugene Court, Sunnyvale, CA 94087 (US). **TAM, Simon**; 569 Keelson Circle, Redwood City, CA 94065 (US).

(74) Agents: **MALLIE, Michael, J.** et al.; Blakely Sokoloff Taylor & Zafman, 12400 Wilshire Boulevard, 7th Floor, Los Angeles, CA 90025 (US).

**Published:**

— *without international search report and to be republished upon receipt of that report*

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: AN APPARATUS FOR THERMAL MANAGEMENT OF MULTIPLE CORE MICROPROCESSORS

(57) Abstract: An apparatus for managing the temperature of an integrated circuit having a multiple core microprocessor is described. Specifically, thermal sensors are placed at potential hot spots throughout each microprocessor core. A thermal management unit monitors the thermal sensors. If a thermal sensor identifies a hot spot, the thermal management unit adjusts the operating frequency and voltage of that microprocessor core accordingly.

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